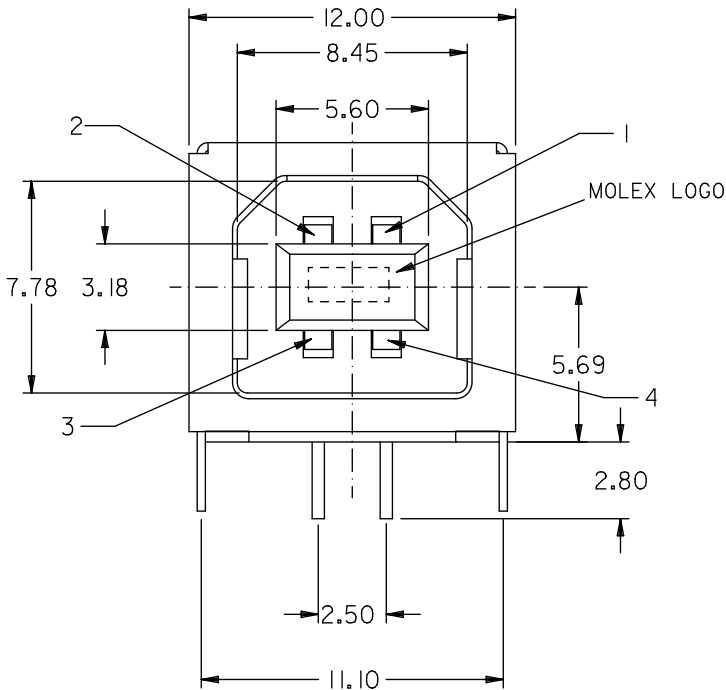
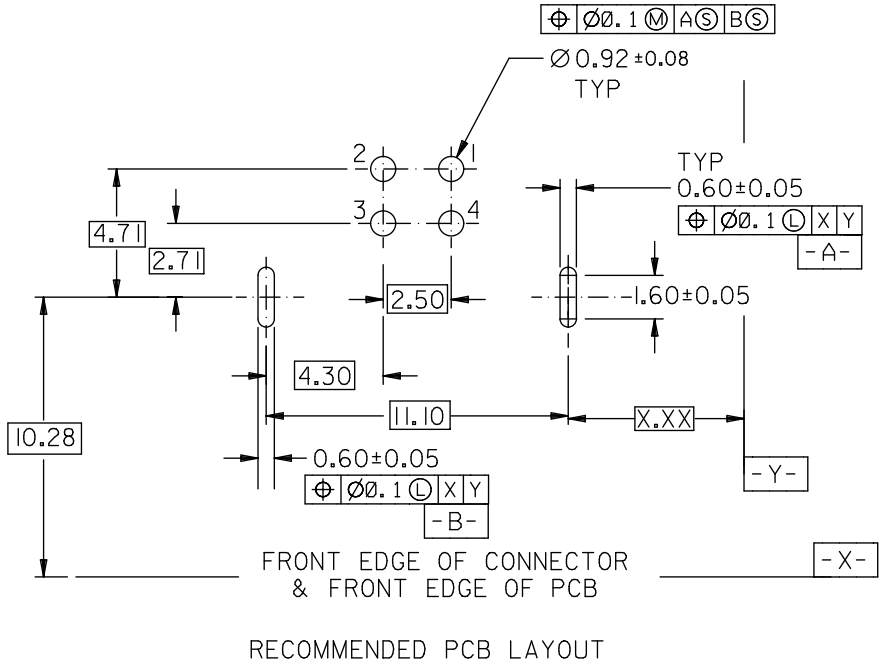
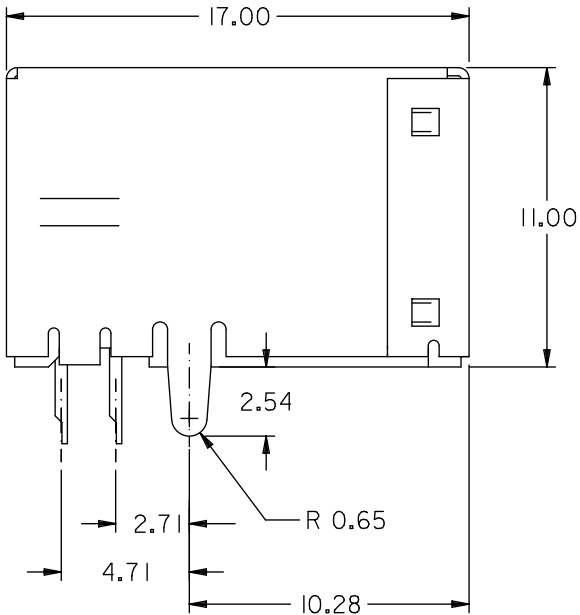
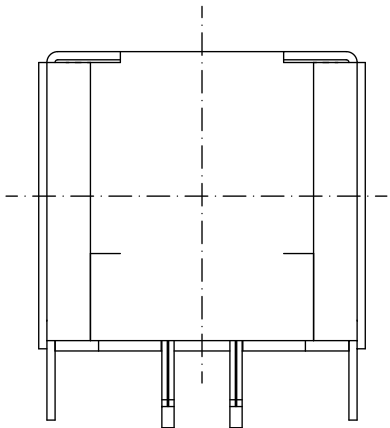
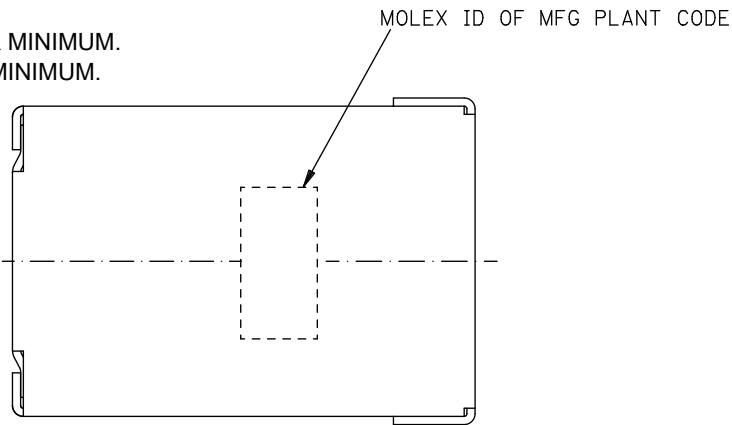
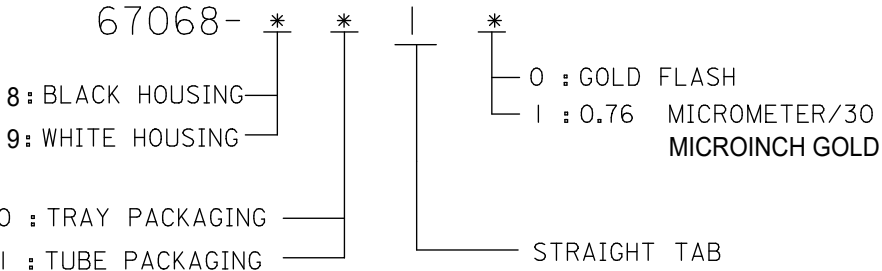

1

NOTES:
1.MATERIAL:
HOUSING:
(a) HIGH TEMP.NYLON ,GLASS FIBER FILLED ,UL 9 V-0,COLOR:BLACK.
(b)POLYESTER ,GLASS FIBER FILLED ,UL 94 V-0 ,COLOR:WHITE.
TERMINAL: PHOSPHOR BRONZE
METAL SHEEL:COPPER ALLOY
2. PLATING:
TERMINAL:
CONTACT AREA:
(c) GOLD FLASH.
(d)GOLD (Au).THICKNESS= 30 MICROINCH MINIMUM./0.76 MICROMETER MINIMUM.
SOLDER TAIL :PURE TIN (Sn) THICKNESS = 75 MICROINCH MINIMUM./1.9 MICROMETER MINIMUM.
UNDER PLATE:NICKEL (Ni),THICKNESS= 50 MICROINCH MINIMUM./1.27 MICROMETER MINIMUM.
METAL SHELL:
PLATING: OVERALL PLATE:NICKEL (Ni),ALL OVER SURFACE.THICKNESS :
50 MICROINCH MINIMUM./1.27 MICROMETER MINIMUM.
3. DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER
RECOMMENDED PCB THICKNESS : 1.60±0.05.
4.PRODUCT SPECIFICATION :REFER TO PS-67998-0000.



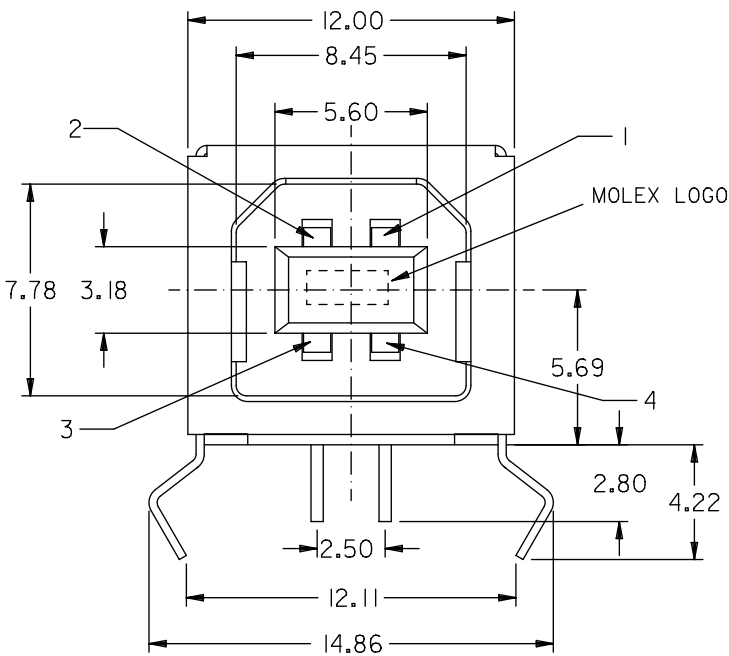
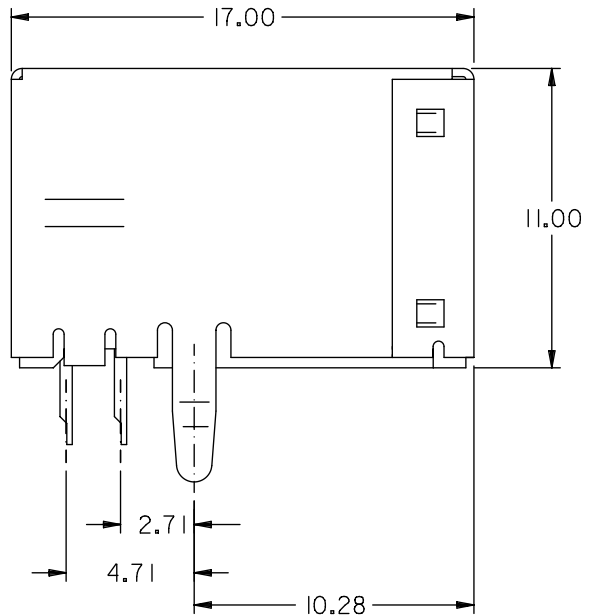
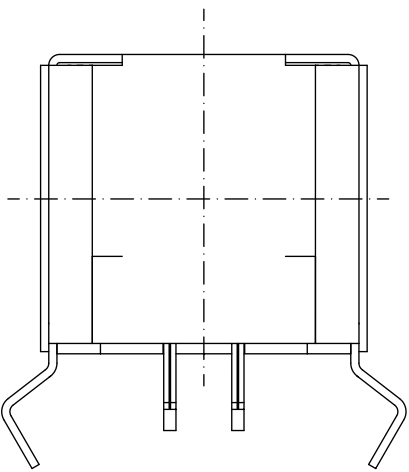
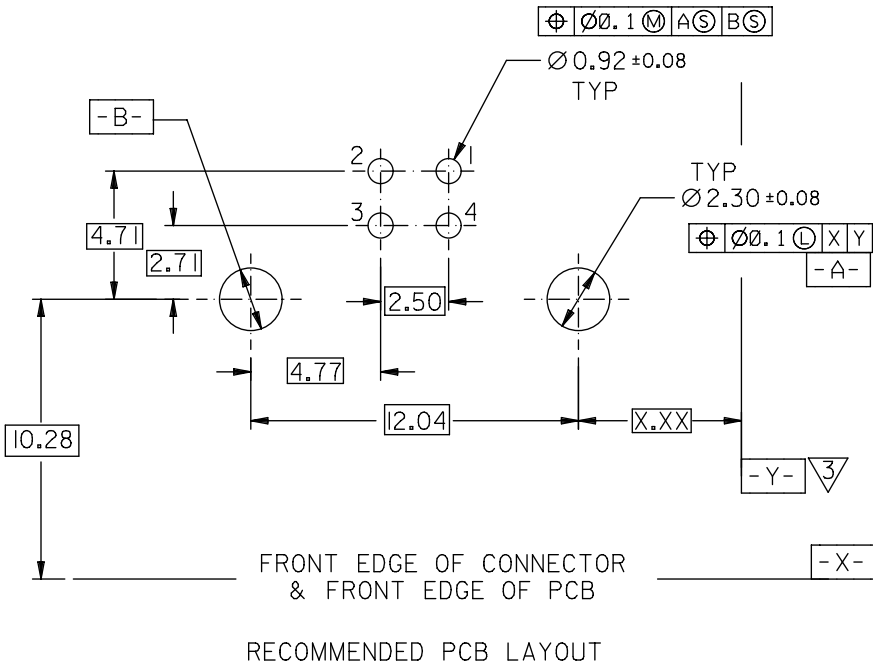
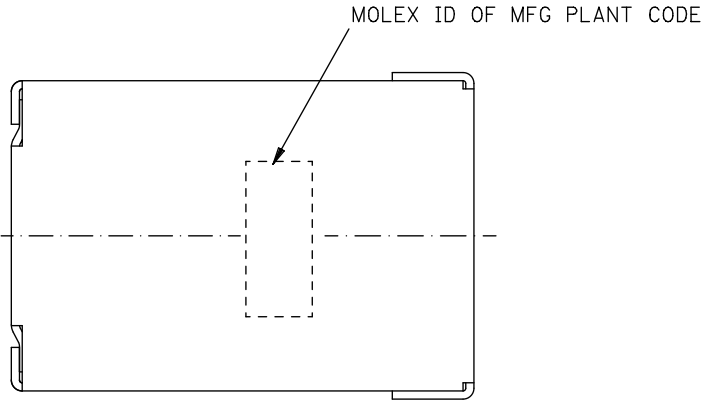
PART NUMBER LEGEND:



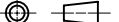
	HOUSING COLOR	PLATING
67068-8010	(a)BLACK	(c)GOLD FLASH
67068-8011	(a)BLACK	(d)30MICROINCH GOLD
67068-9011	(b)WHITE	(d)30MICROINCH GOLD

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											
FUNCTIONAL SYMBOLS	DIMENSION UNITS		SCALE	CURRENT REV DESC:				molex USB B TYPE CONNECTOR KINK TYPE BOARDLOCK LEAD-FREE			
	mm		1:1								
	GENERAL TOLERANCES (UNLESS SPECIFIED)										
	ANGULAR TOL ± 3.0 °										
	4 PLACES		±								
DIVISIONAL SYMBOLS	3 PLACES		±	EC NO: 802815				PRODUCT CUSTOMER DRAWING			
	2 PLACES		± 0.25	DRWN: KCHENG06 2024/09/02							
	1 PLACE		± 0.25	CHK'D: HORACM1 2024/10/31							
	0 PLACES		±	APPR: HORACM1 2024/10/31							
	INITIAL REVISION:				DOCUMENT NUMBER				DOC TYPE	DOC PART	REVISION
DRWN: DHU 2004/11/24				SD-67068-003				PSD	001	B	
APPR: YTYAP 2004/11/25				MATERIAL NUMBER				CUSTOMER		SHEET NUMBER	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIRD ANGLE PROJECTION		DRAWING	SERIES	GENERAL MARKET		2 OF 3	
						B-SIZE	67068				

NOTES:
1.MATERIAL:
HOUSING:
(a) HIGH TEMP.NYLON ,GLASS FIBER FILLED ,UL 9 V-0,COLOR:BLACK.
(b)POLYESTER ,GLASS FIBER FILLED ,UL 94 V-0 ,COLOR:WHITE.
TERMINAL: PHOSPHOR BRONZE
METAL SHEEL:COPPER ALLOY
2. PLATING:
TERMINAL:
CONTACT AREA:
(c) GOLD FLASH.
(d)GOLD (Au).THICKNESS= 30 MICROINCH MINIMUM./0.76 MICROMETER MINIMUM.
SOLDER TAIL :PURE TIN (Sn) THICKNESS = 75 MICROINCH MINIMUM./1.9 MICROMETER MINIMUM.
UNDER PLATE:NICKEL (Ni),THICKNESS= 50 MICROINCH MINIMUM./1.27 MICROMETER MINIMUM.
METAL SHELL:
PLATING: OVERALL PLATE:NICKEL (Ni),ALL OVER SURFACE.THICKNESS :
50 MICROINCH MINIMUM./1.27 MICROMETER MINIMUM.
3. DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER
RECOMMENDED PCB THICKNESS : 1.60±0.05.
4.PRODUCT SPECIFICATION :REFER TO PS-67998-0000.



	HOUSING COLOR	PLATING
67068-7041	(a)BLACK	(d)30MICROINCH GOLD

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION													
FUNCTIONAL SYMBOLS	DIMENSION UNITS		SCALE	CURRENT REV DESC:					molex USB B TYPE CONNECTOR KINK TYPE BOARDLOCK LEAD-FREE				
	mm	1:1	EC NO: 802815 DRWN: KCHENG06 CHK'D: HORACM1 APPR: HORACM1 INITIAL REVISION: DRWN: DHU APPR: YTYAP										
GENERAL TOLERANCES (UNLESS SPECIFIED)													
ANGULAR TOL ± 3.0 °													
DIVISIONAL SYMBOLS	4 PLACES		±	2024/09/02					PRODUCT CUSTOMER DRAWING				
	3 PLACES		±	2024/10/31									
	2 PLACES		± 0.25	2024/10/31					DOCUMENT NUMBER		DOC TYPE	DOC PART	REVISION
	1 PLACE		± 0.25	2004/11/24 2004/11/25					SD-67068-003		PSD	001	B
	0 PLACES		±						THIRD ANGLE PROJECTION		DRAWING	SERIES	MATERIAL NUMBER
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					B-SIZE	67068			GENERAL MARKET		3 OF 3	

10 9 8 7 6 5 4 3 2 1

NOTES :

1. MATERIAL :

HOUSING : (a) HIGH TEMP. NYLON, GLASS FIBER FILLED,UL94V-0, COLOR: BLACK,

(b) POLYESTER , GLASS FIBER FILLED,UL94V-0, COLOR: WHITE,

TERMINAL : PHOSPHOR BRONZE

METAL SHELL : COPPER ALLOY

2. PLATING :

TERMINAL :

CONTACT AREA : (a) GOLD FLASH.

(b) GLOD (Au), THICKNESS = 30 MICROINCH MINIMUM.
/0.76 MICROMETER MINIMUM.

SOLDER TAIL :

PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM .
/1.9 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.

METAL SHELL :

PURE TIN(Sn) THICKNESS= 50 MICROINCH MINIMUM.
/1.27 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.

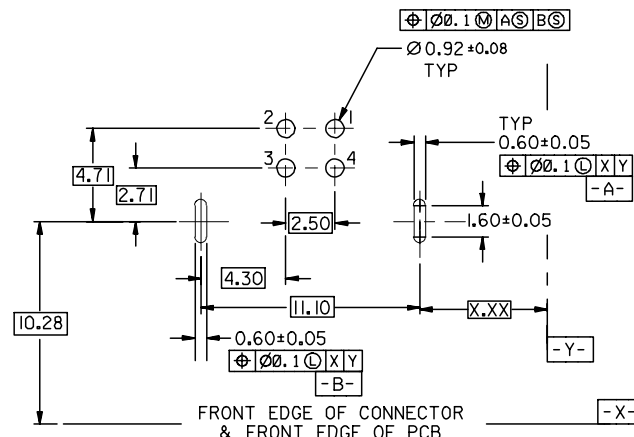
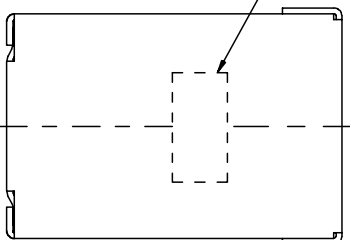
/1.27 MICROMETER MINIMUM.

3 DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER

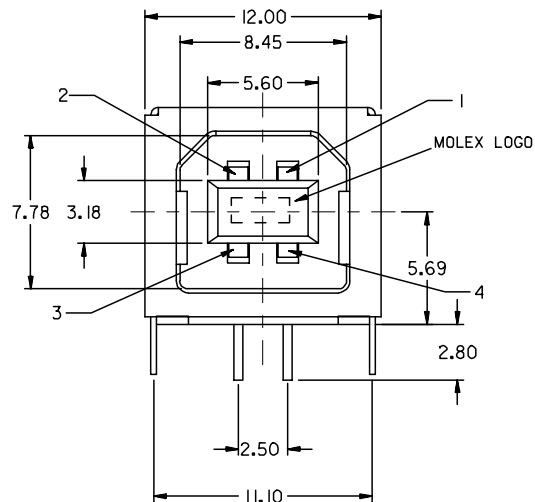
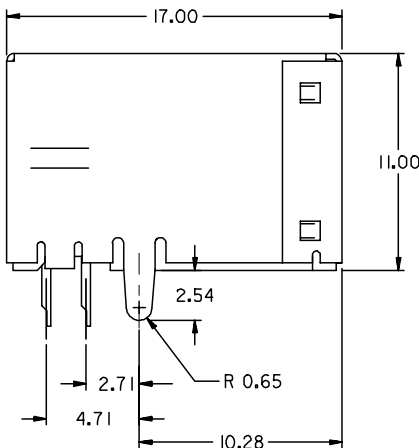
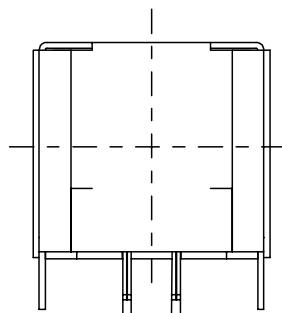
RECOMMENDED PCB THICKNESS : 1.60±0.05

4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000

MOLEX ID OF MFG PLANT CODE



RECOMMENDED PCB LAYOUT



PART NUMBER LEGEND:

67068-

8 : BLACK HOUSING

9 : WHITE HOUSING

0 : TRAY PACKAGING

1 : TUBE PACKAGING

0 : GOLD FLASH

1 : 0.76 MICROMETER/30

MICROINCH GOLD

STRAIGHT TAB

NEW RELEASE
EC NO: SH2005-0142
DRWN: DAVID HU 2004/11/5
CHKD:HARVEY 2004/11/25
APPR:YTYAP 2004/11/25

QUALITY SYMBOLS

▽=0

▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.25	± --- 2004/11/05
1 PLACE	± 0.25	± ---

ANGULAR ± 3 °

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY

DRAWN BY	DATE
DAVID HU	2004/11/05
CHECKED BY	DATE
	2004/11/05
APPROVED BY	DATE

MATERIAL NO.

SEE NOTES

SCALE
4:1

DESIGN UNITS
METRIC

THIRD ANGLE
PROJECTION

TITLE
USB B TYPE CONNECTOR
WITH STRAIGHT TAB
(LEAD-FREE)

MOLEX INCORPORATED

DOCUMENT NO.
SD-67068-003

SHEET NO.
2

8

7

6

5

4

3

2

1

NOTES :

1. MATERIAL :

HOUSING : (a) HIGH TEMP. NYLON, GLASS FIBER FILLED, UL94V-0, COLOR: BLACK,

TERMINAL : PHOSPHOR BRONZE

METAL SHELL : COPPER ALLOY

2. PLATING :

TERMINAL :

CONTACT AREA : (a) GOLD FLASH.

(b) GLOD (Au), THICKNESS = 30 MICROINCH MINIMUM.
/0.76 MICROMETER MINIMUM.

SOLDER TAIL :

PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM .
/1.9 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.

/1.27 MICROMETER MINIMUM.

METAL SHELL :

PURE TIN(SN), THICKNESS= 50 MICROINCH MINIMUM.
/1.27 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.

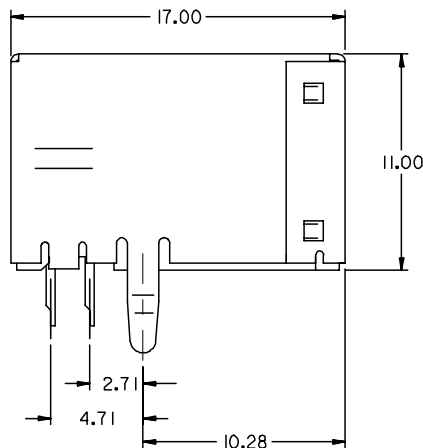
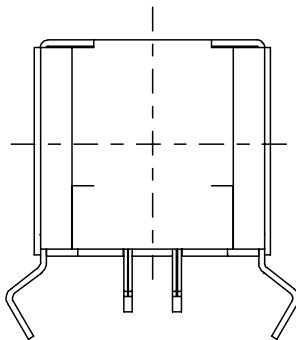
/1.27 MICROMETER MINIMUM.

DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER

RECOMMENDED PCB THICKNESS : 1.60±0.05

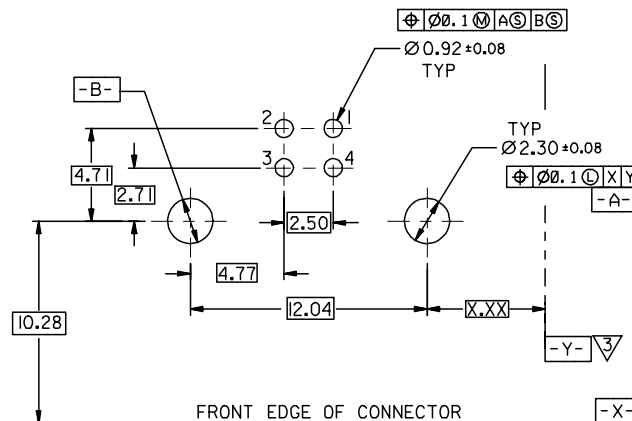
4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000

MOLEX ID OF MFG PLANT CODE

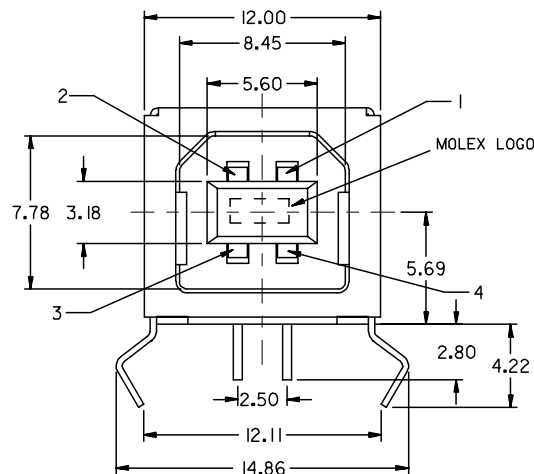


PART NUMBER LEGEND:

67068- 7041

FRONT EDGE OF CONNECTOR
& FRONT EDGE OF PCB

RECOMMENDED PCB LAYOUT



MOLEX LOGO

						MATERIAL : SEE NOTES	 MOLEX TAIWAN LTD. SHEET 3 OF 4	
						FINISH : SEE NOTES		
						WIRE RANGE :		
						INS. RANGE :		
						ENG. NO.:	SD-67068-003	REV A
A	NEW RELEASE FOR LEAD-FREE			DAVID HU	2004/11/5			
LTR	REVISION RECORD	ECN	DR	DATE	DRAWN BY 2004/11/5 DAVID HU	CHK'D BY	TITLE : HIGH TEMP.USB B TYPE CONNECTOR KINK TYPE BOARD LOCK (LEAD-FREE)	
REVISE ONLY ON CAD SYSTEM					APPR'D BY	SCALE 4 : 1		

ENG. NO.

EDP NO.

SIMILAR ITEM

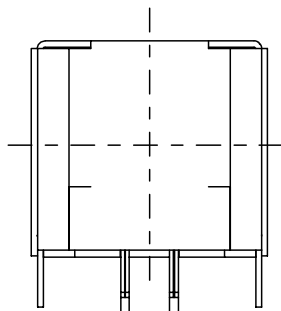
CAD FILE :

DO NOT SCALE DRAWING

DO NOT SCALE DRAWING

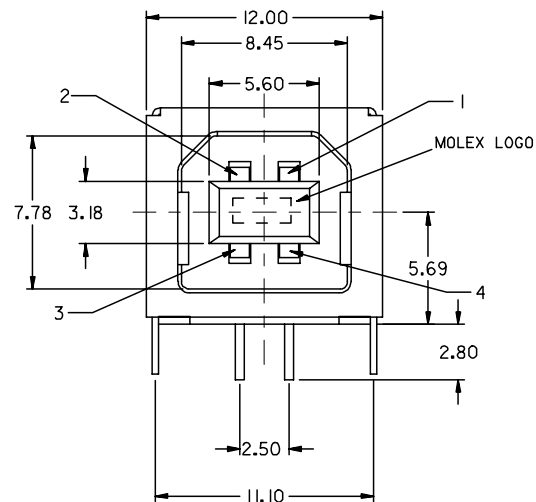
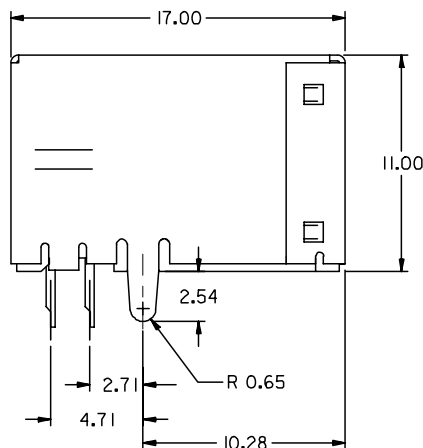
4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000

RECOMMENDED PCB LAYOUT



PART NUMBER LEGEND:

67068- 7051



					MATERIAL :	SEE NOTES	 MOLEX TAIWAN LTD. SHEET 4 OF 4
					FINISH :	SEE NOTES	
					WIRE RANGE :	GENERAL TOLERANCES ANGLE : ± 3° DIM : ± .25/.010	
					INS. RANGE :	ENG. NO.: SD-67068-003	
A	NEW RELEASE FOR LEAD-FREE		DAVID HU	2004/11/5	DRAWN BY ^{2004/11/5} DAVID HU	CHK'D BY	
LTR	REVISION RECORD	ECN	DR	DATE	APPR'D BY	SCALE 4 : 1	
REVISE ONLY ON CAD SYSTEM							TITLE : HIGH TEMP./USB B TYPE CONNECTOR WITH STRAIGHT TAB (LEAD-FREE)

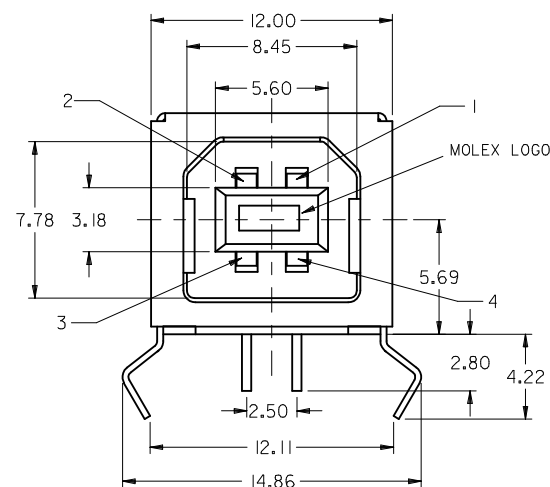
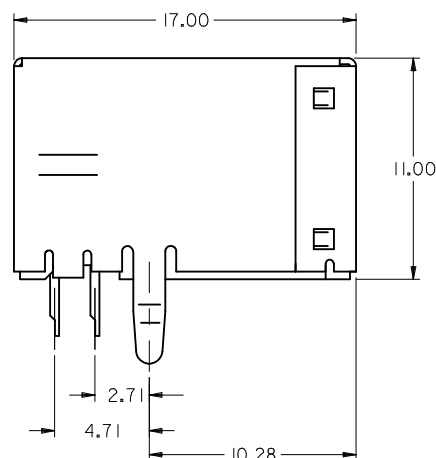
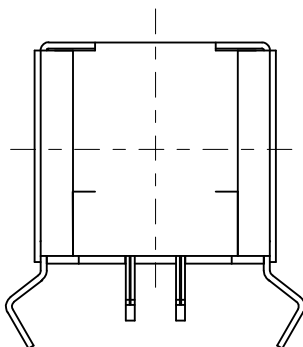
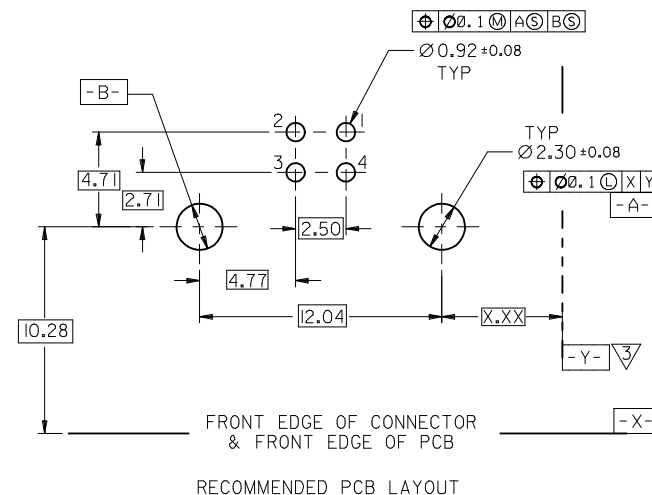
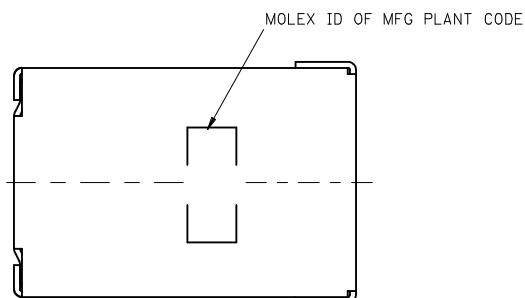
1.MATERIAL:
HOUSING:
(a)HIGH TEMP,NYLON,GLASS FIBRE FILLED,UL94V-0,COLOR: 8:BLACK
(b)POLYESTER(PBT),30% GLASS FIBER FILLED,UL94V-0,COLOR: 9:WHITE
TERMINAL: PHOSPHOR BRONZE
METAL SHELL: COPPER ALLOY

2.PLATING:
TERMINAL:
(c)GOLD FLASH ON CONTACT AREA,75 MICROINCH MINIMUM PURE TIN(Sn)
ON SOLDER TAIL,UNDER 50 MICROINCH MINIMUM NICKEL(Ni) PLATE.
(d)30 MICROINCH MINIMUM GOLD(Au) ON CONTACT AREA,75 MICROINCH
MINIMUM PURE TIN(Sn) ON SOLDER TAIL,UNDER 50 MICROINCH
MINIMUM NICKEL(Ni) PLATE.
(e)GOLD FLASH ON CONTACT AREA,75 MICROINCH MINIMUM MATTE TIN(Sn)
ON SOLDER TAIL,UNDER 50 MICROINCH MINIMUM NICKEL(Ni) PLATE.
(f)30 MICROINCH MINIMUM GOLD(Au) ON CONTACT AREA,75 MICROINCH
MINIMUM MATTE TIN(Sn) ON SOLDER TAIL,UNDER 50 MICROINCH
MINIMUM NICKEL(Ni) PLATE.

METAL SHELL:
(g)50 MICROINCH MINIMUM PURE TIN(Sn),UNDER 50 MICROINCH MINIMUM
NICKEL(Ni) PLATE.
(h)50 MICROINCH MINIMUM MATTE TIN(Sn),UNDER 50 MICROINCH MINIMUM
NICKEL(Ni) PLATE.

3.DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER.
RECOMMENDED PCB THICKNESS : 1.60±0.05

4.PRODUCT SPECIFICATION : REFER TO PS-67998-0000



P/N	HOUSING COLOR	PLATING
67068-8000	BLACK	GOLD FLASH SEE NOTES[2-(c),2-(g)]
67068-8001	BLACK	30MICROINCH Au SEE NOTES[2-(d),2-(g)]
67068-9000	WHITE	GOLD FLASH SEE NOTES[2-(c),2-(g)]
67068-9001	WHITE	30MICROINCH Au SEE NOTES[2-(d),2-(g)]
67068-8012 	BLACK	30MICROINCH Au SEE NOTES[2-(f),2-(h)]
67068-8013 	BLACK	GOLD FLASH SEE NOTES[2-(e),2-(h)]

REVISED	EC NO: SH2007-0468		2007/01/19	DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	2007/01/19		2007/01/19			MM ONLY		4:1	METRIC				
	DRWN:HYHE01		2007/01/19			DRAWN BY DATE		TITLE		USB B TYPE CONNECTOR LEAD-FREE			
	CHKD: IWANG		2007/01/19			CHECKED BY DATE							
	APPR: JINCHEN		2007/01/26			HARVEY 2004/11/05							
						APPROVED BY DATE		MOLEX MOLEX INCORPORATED					
						MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
						SEE NOTES		SD-67068-004		1 OF 1			